

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 2-3 and 10-15 without prejudice and amend claims 1, 4-9, 16, 20 and 21 as follows:

LISTING OF CLAIMS:

1. (Currently Amended) A method of patterning a thin film comprising the steps of:

forming ~~at least one strippable conductive film~~ an insulating organic film that is strippable by an organic solvent on a surface of a thin film to be patterned;

forming a conductive film on said insulating organic film;

forming a mask on said ~~at least one strippable~~ conductive film;

patterning said thin film to be patterned by dry etching using said mask;

and

removing said ~~at least one strippable~~ conductive film and said mask by removing said insulating organic film using an organic solvent.

2. (Canceled)

3. (Canceled)

4. (Currently Amended) The method as claimed in claim [[3]] 1, wherein said mask is formed by forming a resist film on said conductive film and then by patterning said resist film using an electron beam writing method.

5. (Currently Amended) The method as claimed in claim 3 1, wherein said conductive film is a metallic material film.

6. (Currently Amended) The method as claimed in claim 3 1, wherein said conductive film is a conductive organic film.

7. (Currently Amended) The method as claimed in claim 3 1, wherein said conductive film is a grounded film.

8. (Currently Amended) A method of manufacturing a thin-film device, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming ~~at least one strippable conductive film~~ an insulating organic film that is strippable by an organic solvent on a surface of a thin film to be patterned;

forming a conductive film on said insulating organic film;

forming a mask on said ~~at least one strippable~~ conductive film;

patterning said thin film to be patterned by dry etching using said mask;

and

removing said ~~at least one strippable~~ conductive film and said mask by removing said insulating organic film using an organic solvent.

9. (Currently Amended) A method of manufacturing a thin-film magnetic head, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

~~forming at least one strippable conductive film~~ an insulating organic film that is strippable by an organic solvent on a surface of a thin film to be patterned;

forming a conductive film on said insulating organic film;

forming a mask on said ~~at least one strippable~~ conductive film;

patterning said thin film to be patterned by dry etching using said mask;

and

~~removing said at least one strippable conductive film~~ and said mask by removing said insulating organic film using an organic solvent.

Claims 10-15. (Canceled)

16. (Currently Amended) A method of patterning a thin film comprising the steps of:

forming at least an insulating organic film that is strippable by an organic solvent and a conductive film on a surface of a thin film to be patterned;

forming a resist film on said conductive film;

patterning said resist film using an electron beam writing method;

patterning said thin film to be patterned by dry etching using said patterned resist film as a mask; and

~~removing said at least insulating organic film and~~ conductive film and said mask by removing said at least insulating organic film using an organic solvent.

17. (Original) The method as claimed in claim 16, wherein said conductive film is a metallic material film.

18. (Original) The method as claimed in claim 16, wherein said conductive film is a conductive organic film.

19. (Original) The method as claimed in claim 16, wherein said conductive film is a grounded film.

20. (Currently Amended) A method of manufacturing a thin-film device, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming at least an insulating organic film that is strippable by an organic solvent and a conductive film on a surface of a thin film to be patterned;

forming a resist film on said conductive film;

patterning said resist film using an electron beam writing method;

patterning said thin film to be patterned by dry etching using said patterned resist film as a mask; and

removing said ~~at least insulating organic film and~~ conductive film and said mask by removing said at least insulating organic film using an organic solvent.

21. (Currently Amended) A method of manufacturing a thin-film magnetic head, at least a part of a thin-film pattern being fabricated by using a thin-film patterning method, said thin film patterning method comprising the steps of:

forming at least an insulating organic film that is strippable by an organic solvent and a conductive film on a surface of a thin film to be patterned;

forming a resist film on said conductive film;

patterning said resist film using an electron beam writing method;

patterning said thin film to be patterned by dry etching using said patterned resist film as a mask; and

removing said ~~at least insulating organic film and~~ conductive film and said mask by removing said at least insulating organic film using an organic solvent.